

Amphenol®



Server Power



The undisputed leader in interconnect systems for harsh environment applications

Company Introduction

Manufacturing connectors since 1932, we take pride that Amphenol Industrial Global Operations (AIGO) is the undisputed leader in interconnect systems for harsh environment applications. Such applications require a high degree of engineering sophistication and precision manufacturing capability. Innovations such as our RADSOK® contact technology can supply gains of up to 50% in current carrying capability through the same size pin vs traditional contact designs. Connectors utilizing the RADSOK® technology outperform conventional power interconnect products and are a better choice for the high current needs demanded by sophisticated electronics.

AIGO's product lines consist of rectangular, standard, miniature, fiber optic, EMI/EMP filter and a variety of special application connectors. Additionally, we manufacture value-add flex circuit and cable assemblies.

Our global manufacturing facilities include locations in Sidney, NY, Fraser, MI, Midland, TX, Shenzhen and Zhuhai, China, Winnipeg, Canada, and Nogales, Mexico. Our Sidney, NY facility is both ISO9001 certified and qualified to MIL-STD-790 requirements.

The Server Environment

Modern servers are capable of millions of transactions per second. They consume significant amounts of power, and produce tremendous amounts of heat while conducting the high amperage to manage these transactions.

Excessive heat can cause malfunctions and irreversible damage to servers while being expensive to manage. Therefore, minimizing temperature rise is a key concern when designing power systems for data centers.

AIGO has industry leading experience engineering high current and high density interconnect solutions. Our RADSOK® technology and our proven engineering experience for harsh environments enable Amphenol Industrial Global Operations to develop optimal solutions for server power interconnect needs.

RADSOK® Technology Advantages

RADSOK'S twisted grid configuration allows for 50% more current to pass through the same size pin, while providing increased reliability, ampacity and cycle durability as well as lower insertion force, T-rise and voltage drop.

HIGH RELIABILITY

Unique RADSOK® design and construction technology create an electrical contact interface that exceeds typical interconnect requirements. Applications in aerospace, medical, industrial, automotive, mining, offshore, and other harsh environments depend on the high reliability of Amphenol's RADSOK® technology.

• LOW CONTACT ENGAGEMENT/SEPARATION FORCES

The hyperbolic lamella socket contact construction distributes normal forces over a high percentage of the mating pin surface. This creates a smooth, even engagement effort. This force distribution also contributes to excellent performance in vibration applications with resistance to typical fretting corrosion.

• LOW CONTACT RESISTANCE

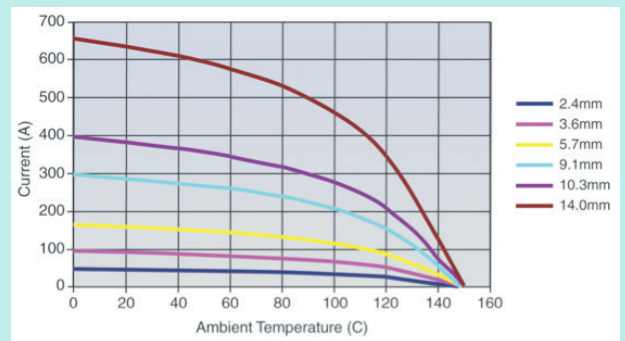
The large interface area between the socket lamella and pin surface result in very low contact resistance, enabling the RADSOK® contacts' high current ratings compared to traditional power contact designs.

• HIGH MATING CYCLE DURABILITY

RADSOK® contacts with typical silver plating finishes have demonstrated survival of 20,000 mating cycles. Specialized plating and contact lubricants can extend cycle life to 200,000 matings or higher. Even with continuous exposure to harsh environmental abuse (salt, sand, and high humidity), RADSOK® contacts have been tested to maintain low contact resistance beyond 10,000 mating cycles.

RADSOK® Derating Chart – Temperature vs. Current

Based on single conductors in free air. Wire cross-section same size as pin contact cross-sectional area.



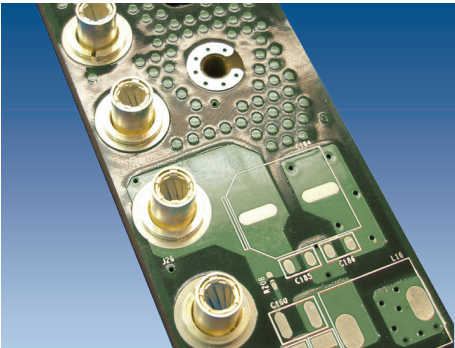
RADSOK® Power to Board Connectors

High speed and high density electronics have driven demand for significant increases in the amount of power needed for power to board applications. To meet the need for higher current density interconnects Amphenol Industrial Global Operations developed the RADSOK® Power to Board series of connectors. RADSOK® Power to Board solutions facilitate the distribution of power with higher amperage, while allowing the design engineer to achieve size and weight reductions.

Conventional interconnects are limited in their ability to deliver high current without consuming excessive board surface area. The RADSOK® Power to

Board series of connectors incorporates a hyperbolic lamella socket contact construction that provides more contact surface area. The high performance contact enables higher current carrying capabilities with lower temperature rises than traditional contact systems.

Amphenol's RADSOK® Power to Board product line offers many options for delivering high current and single-point connections to the PCB. Please contact your Amphenol Industrial representative for product extensions and custom applications.

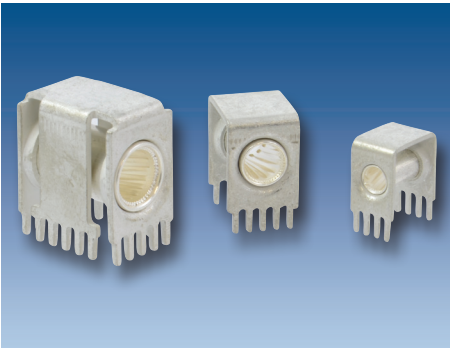


RADSERT™'s compact footprint design can deliver up to 120A of current to the board. The high current density and small surface area connection provides flexibility of board design. RADSERT™ contacts are available in either press-fit or solder termination.

RADSOK® RADSERT™

- High power to board interconnect in a small package
- Hyperbolic socket design ensures many points of contact
- Solder version or pre-loaded RADSERTs are installed during board fabrication
- RADSERT™ 2.4mm (35A), 3.0mm (60A), 3.6mm (70A) 4.8mm (100A) & 6.0mm (120A)
- No special crimp tools required
- No threaded fasteners
- Eliminates risk of PTH cracking or delamination in board
- Faster through-put
- Available in Super Twist (ST)
- RoHS compliant

Part Number	Size	Amps	Termination
10-729398-241	2.4mm	35	Solder Type
10-700813-001	2.4mm	35	Knurl Press Fit
10-729360-001	ST 2.4mm	35	Solder Type
10-700977-001	3.6mm	70	Solder Type
10-700985-001	3.6mm Close End	70	Solder Type
10-707833-001	3.6mm	70	Knurl Press Fit
10-729387-001	ST 3.6mm	70	Solder Type
10-707617-000	ST 3.6mm	70	Knurl Press Fit
10-729220-001	ST 6.0mm	120	Solder Type

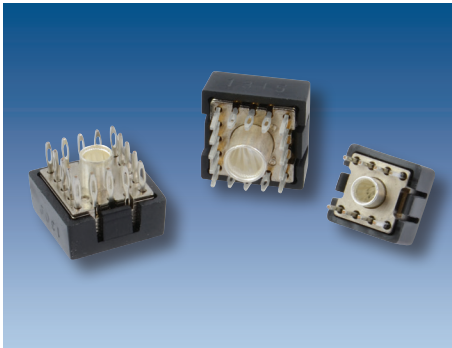


The RADSOK® PGY™ provides a compact and robust right angle power to board interconnect. Designed to mate with either a 3.6mm or 5.7mm pin, The RADSOK® PGY™ can bring up to 120A to the board. The radial design of the RADSOK® contact gives you more contact surface area lowering temperature rise and reducing potential heat related failures.

RADSOK® PGY™

- Orthogonal, co-planar & right angle connections between PCBs or PCB to bus bar
- Compact footprint
- Legs of the PGY distribute high power evenly
- 2.4mm carries up to 35 Amps
- 3.0mm carries up to 60 Amps
- 3.6mm carries up to 70 Amps
- 4.8mm carries up to 100 Amps
- 5.7mm carries up to 120 Amps
- No threaded fasteners
- No special crimp tools required
- Faster through-put
- Available in Super Twist (ST)
- RoHS compliant

Part Number	Size	Amps	Termination
10-700298-000	3.6mm	70	Solder Type
10-729394-000	ST 3.6mm	70	Solder Type
10-700261-000	5.7mm	120	Solder Type
10-700261-000	ST 5.7mm	120	Solder Type



The RADSOK® PowerBlok™'s compact footprint ½" x ½" can supply up to 70A to backplane power connections. Current is distributed over 16 compliant pins. The PowerBlok™ is available for top or bottom entry and offered with a touch-proof cover.

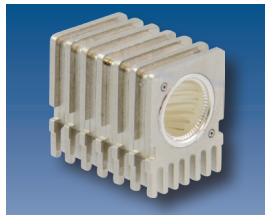
RADSOK® PowerBlok™

- High power to board interconnect in a small package
- Compact footprint 15.7mm x 15.7mm
- RADSOK® 2.4mm, 3.0mm & 3.6mm (35A-60A-70A)
- Backplane power interface with compliant pins for power
- Touchproof cover
- Hyperbolic socket design ensures many points of contact
- Reduces failure modes, eliminates burn outs
- No threaded fasteners
- No special crimp tools required
- Eliminates possible stress fractures in board
- Faster through-put
- Available in Super Twist (ST)
- RoHS compliant

Part Number	Size	Amps	Termination
10-707897-001	ST 2.4mm	35	Press-fit
10-700300-001	ST 3.0mm	60	Press-fit
10-707548-001	ST 3.6mm	70	Press-fit

RADSOK® RadFin™

RADSOK® RadFin™ was designed to address the need for amperes greater than 100A while maintaining a small footprint for PCB applications. Another unique feature of the RadFin™ is its ability to act as a great heat dissipating connector. This dramatically helps reduce T-rise with minimal air-flow required.



- 100A to 300A
- Small form factor, 6.0mm, 8.0mm & 10.0mm
- Also offered with a plastic protective cover and male pin
- Solder tail (Press fit optional)
- 1000A surge – 2 seconds
- Operating temperature can meet -40C to +125C
- Dielectric withstanding voltage is 2000 Vac RMS
- Insulation resistance can meet 5000 M Ohms
- 500 mating cycles – minimum
- Insertion force : Max 7 lbs.; Separation force: Min 1.5 lbs.
- UL94-V0 (self extinguishing)

RADSOK® RADLOK™

Utilizing Amphenol's latest **R4 RADSOK® Technology**, our RADLOK™ product line was designed to be compact and robust. Power Interconnect products in today's market often require additional mounting hardware (e.g. washers, clamps, bolts, nuts, etc.) making them prone to costly labor expenses for installation and routine maintenance. Paired with Amphenol's RADLOK™ PIN, the single finger operation lock feature allows end users to connect any power distribution/storage system in a quick and secure manner. The RADLOK™ product line is the answer to industries where a custom, reliable, easy to install, rugged, and cost effective solution is required.



- Voltage Rating: 1000V
- Current Rating: 70A - 400A
- Tool-Free Mechanical Locking
- High cycle durability (500 mating cycles)
- RoHS complaint
- Available in Black, Red, Orange (custom colors available upon request)

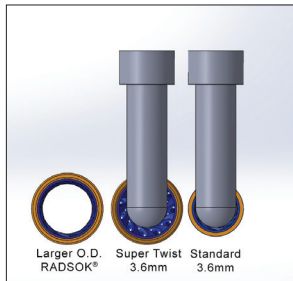
Technical Data

DC Voltage Rating	1000V
DC Current Rating	70A - 400A
Flammability Rating	UL94 V0
Operating Temperature Range	-40° C to 125° C
Mating Cycles	500

RADSOK® Super Twist

Design Background

The RADSOK® Super Twist contact was developed to enable greater radial misalignment tolerance, or "float," in drawer and blindmate applications. Greater radial gatherability is achieved in the Super Twist (ST) contact by adding additional "twist" to a larger RADSOK® contact. Using a larger O.D RADSOK® creates additional I.D clearance for the mating male pin while maintaining electrical and mechanical performance.



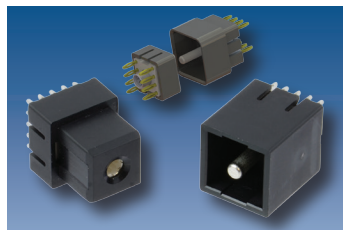
Benefits of using Super Twist RADSOK®

Radial misalignment tolerance is significantly increased, 3x more than standard RADSOK® contacts. The RADSOK® Super Twist contacts are used in applications where mechanical system tolerance is difficult to control in manufacturing and/or assembly, for example, mating multiple positions on a bus bar with poor true positioning to a PCB or pluggable power supply assembly.

Super Twist RADSOK® Offerings

RADSOK® SIZE (mm)	Current Rating Industry Spec	Radial Tolerance mm (Max)	Radial Tolerance inch (Max)
2.4 ST	35A	0.37mm	.014"
3.0 ST	60A	0.37mm	0.14"
3.6 ST	70A	0.67mm	.026"
4.8 ST	100A	0.55mm	.021"
5.7 ST	120A	0.65mm	.026"

RADSOK® RadStack™



RADSOK® RadStack™ was designed to address the need for high current and small foot prints for PCB mezzanine applications.

- 35A to 120A
- Low-profile, 10mm to 50mm in any size increment
- Press fit attachment 35A to 120A
- 1000A surge – 2 seconds
- Operating temperature can meet -40C to +125C
- Dielectric withstanding voltage is 2000 Vac RMS
- Insulation resistance can meet 5000 M Ohms
- Mezzanine heights from 10mm+
- 500 mating cycles – minimum
- Insertion force : Max 4.5 lbs.; Separation force: Min 0.62 lbs. (Each pin)
- UL94-V0 (self extinguishing)

RADSOK® PowerBlok™ WTB (Wire to Board)



- 35A rated single point of contact
- Low profile right angle exit less than ½ inch mated height
- 12-14 AWG crimp contact with insulated housings
- Board receptacle part number: 10-707991-000
- Wire applied right angle pin with latching housing part number: 10-729455-000



AMPHENOL CORPORATION
Amphenol Industrial

Phone: 607-563-5011
40-60 Delaware Avenue
Sidney, NY 13838-1395
www.amphenol-industrial.com

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9